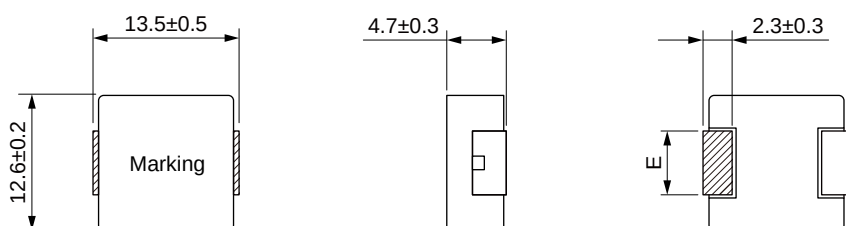


SMD Low Profile High Current Molded Inductor Size 1350

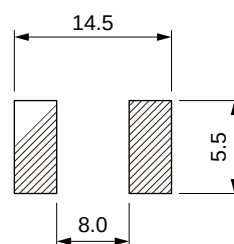


- Shielded construction
 - Capable of corresponding high frequency .
 - Low loss realized with low DCR.
 - High performance (Isat) realized by metal dust core.
 - Ultra low buzz noise, due to composite construction.
 - 100% Lead(Pb)-Free and RoHS compliant.
 - AEC-Q200 qualified
 - Operating temperature: -55 to +155 °C(including self-temperature rise)
 - Quantity: 500PCS
-
- Noise filter for various drive circuitry requiring high temp. operation and peak current handling capability.
 - Boost-Converter
 - Buck-Converter DC/DC

Dimensions: [mm]



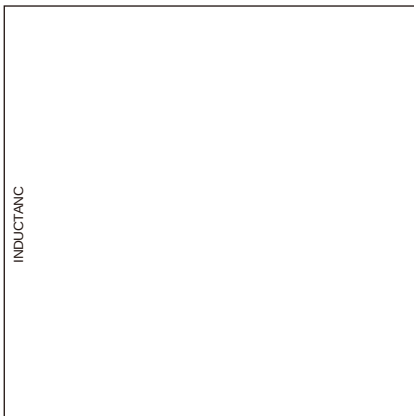
Land Pattern: [mm]



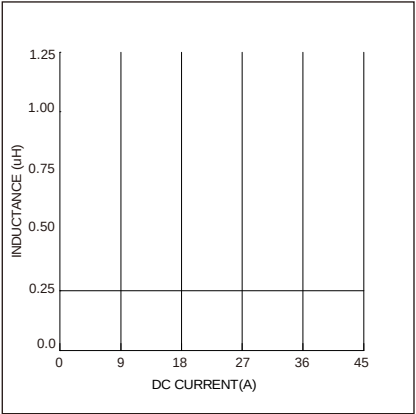
Electrical Properties:

MDSA1350-R22M	0.22	±20%	54.7	64.8	0.50	0.62	4.0±0.3
MDSA1350-R47M	0.47	±20%	38.0	64.8	0.78	0.91	4.0±0.3
MDSA1350-R68M	0.68	±20%	33.8	50.0	1.33	1.58	4.0±0.3
MDSA1350-1R0M	1.00	±20%	29.9	39.8	1.61	1.91	4.0±0.3
MDSA1350-1R5M	1.50	±20%	24.9	30.7	3.22	3.83	4.7±0.3
MDSA1350-2R2M	2.20	±20%	17.0	25.9	4.10	4.82	4.7±0.3
MDSA1350-3R3M	3.30	±20%	15.4	22.8	6.03	7.00	4.7±0.3
MDSA1350-4R7M	4.70	±20%	13.8	18.4	8.82	10.2	4.7±0.3
MDSA1350-6R8M	6.80	±20%	11.7	16.3	13.0	16.0	4.7±0.3
MDSA1350-100M	10.0	±20%	10.0	12.8	19.2	22.2	4.7±0.3
MDSA1350-150M	15.0	±20%	9.38	10.8	30.1	36.3	4.7±0.3

Typical Electrical Characteristics:



Typical Electrical Characteristics:

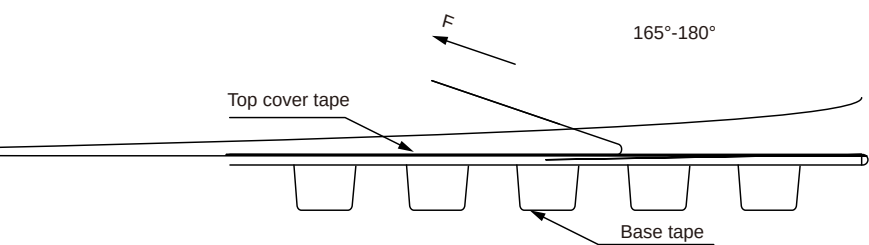


Soldering Reflow:

Packaging Information:

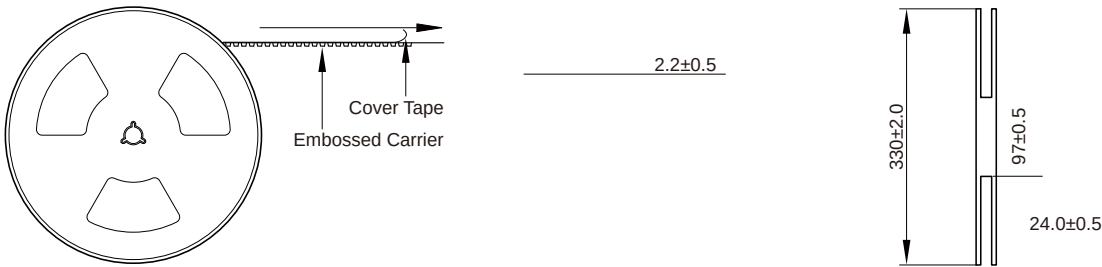
Tape Dimension :

Peel force of top cover tape:

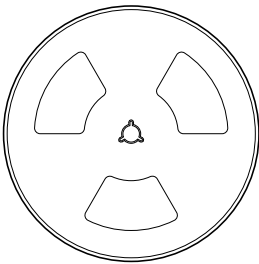


R f c nccj dmpac md rmn amtcp r_nc qf_jj `c `crucc l ., / rm /,1 L

Reel Dimension : [mm]



Packaging Quantity:



3 . . Naq-Pccj

0 Pccj -G l l cp `mv& / . . . Naq'

0 G l l cp `mv-A\_prm l `mv&0 l Naq'

Cautions and Warnings:

Storage Conditions :

Operation Instructions: